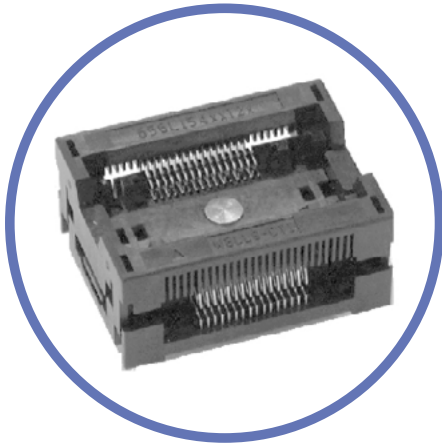


656T SERIES

THERMALLY ENHANCED XSOP



Features

- Compact size for maximum board density
- Wide target area for easy entry and removal of IC leads
- Dual face-wipe contacts for long, dependable life
- Excellent component clearance under the socket
- Four high corner standoffs for easy inspection and cleaning of the PC board
- For temperatures up to 150°C; for higher temperature applications consult the factory

MATERIALS AND SPECIFICATIONS

Socket Body	PEI or Equivalent
Contact	Beryllium Copper Alloy
Contact Plating	Gold over Nickel
Contact Normal Force	35–45 grams
Contact Resistance	50 mΩ max
Dielectric	300V AC for 1 Minute
Temperature Rating	150°C
Dielectric	5,000 MΩ @ 500V DC
Durability	10,000 cycles min.
Thermal Pin Power Dissipation	2W Minute

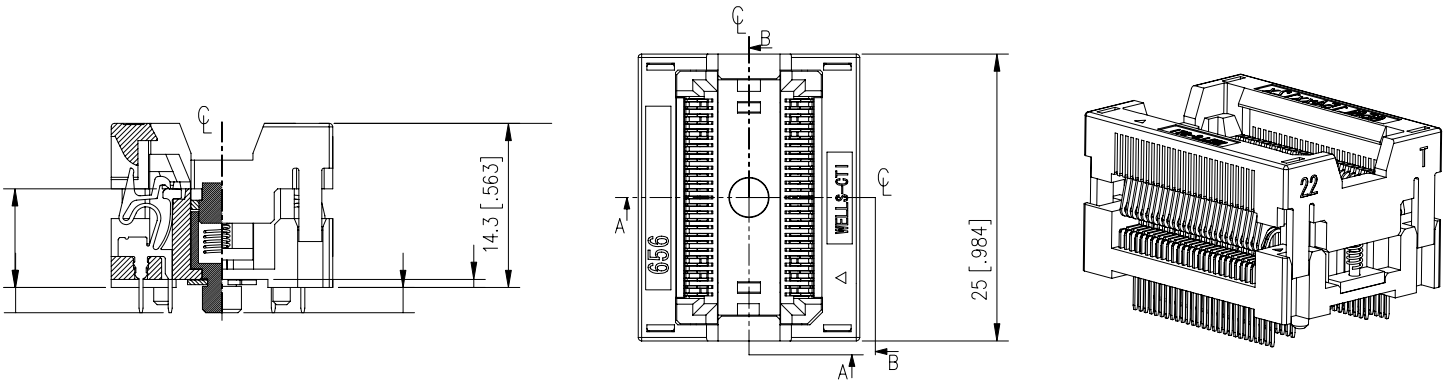
Lead Count	Pitch e (mm)	Package Dimensions (mm)			Part Number	Socket Dimensions (mm)	
		Width (E1)	Lead Width (max) (E)	Length (D)		Length (A)	Width (B)
32	0.65	7.50	10.30	11.10 max	656L1543212T	25.00	19.30
36	0.65	7.50	10.30	12.79 max	656L1543612T	25.00	19.30
52	0.65	7.50	10.30	18.10 max.	656L1545212T	25.00	19.30
54	0.65	7.50	10.30	18.00 max.	656L1542212T	25.00	19.30

Note: T = with thermal contact



DIMENSIONS AND DIAGRAMS

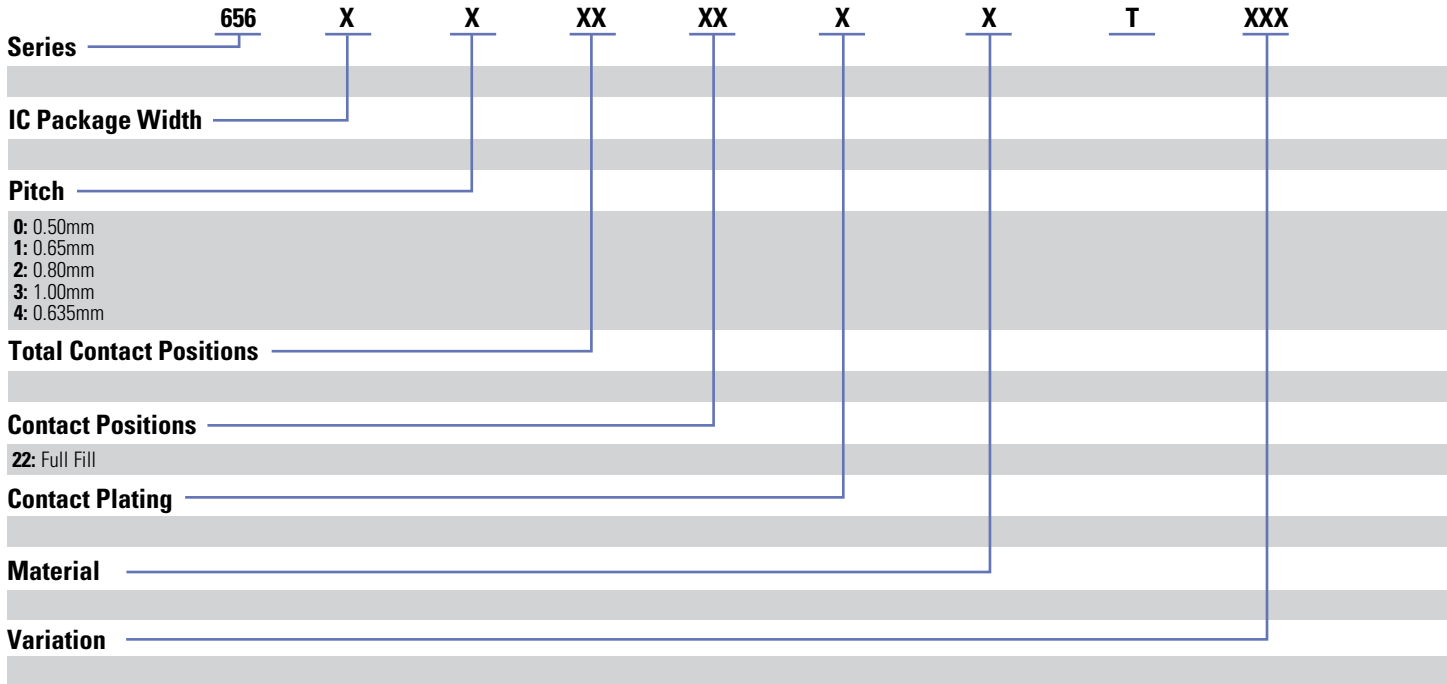
Dimensions in mm (inches)





DESCRIPTION & ORDERING INFO

Example : 656 X X XX XX X X T XXX



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